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APPLICATION I	10 E	ILING DATE	FIRST MAN (FR. DUITNIMO)			
		ILING DATE	FIRST NAMED INVENTOR  Takashi Ohsumi	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/714,962		11/18/2003		OKI 389	4582	
23995	7590	00,02,2004		EXAMINER		
RABIN & Berdo, PC 1101 14TH STREET, NW				CLARK, JASMI	CLARK, JASMINE JHIHAN B	
SUITE 500 WASHINGTON, DC 20005			*	ART UNIT	PAPER NUMBER	
WASHIN	GION, DC	20005		2815		

DATE MAILED: 06/02/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

· · · · · · · · · · · · · · · · · · ·	Application No.	Applicant(s)
	10/714,962	OHSUMI, TAKASHI
Office Action Summary	Examin r	Art Unit
	Jasmine J Clark	2815
Th MAILING DATE of this communication app Period for Reply	pears on the cover she t with t	he correspondence address
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period w Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing	36(a). In no event, however, may a reply within the statutory minimum of thirty (30 will apply and will expire SIX (6) MONTHS cause the application to become ABANT	be timely filed  b) days will be considered timely.  from the mailing date of this communication.
earned patent term adjustment. See 37 CFR 1.704(b).  Status		
1) Responsive to communication(s) filed on		
	action is non-final.	
3) Since this application is in condition for allowan		prosecution as to the merits is
closed in accordance with the practice under E		
Disposition of Claims	,	,,
· · · · · <u>- · · · · · · · · · · · · · ·</u>		
<ul> <li>4) ☐ Claim(s) 1-20 is/are pending in the application.</li> <li>4a) Of the above claim(s) is/are withdraw</li> <li>5) ☐ Claim(s) 16 is/are allowed.</li> </ul>		
<u> </u>		
6)⊠ Claim(s) <u>1,4,11,14,17 and 20</u> is/are rejected. 7)⊠ Claim(s) <u>2,3,5-10,12,13,15,18 and 19</u> is/are ob	iostad to	
8) Claim(s) are subject to restriction and/or	•	
	ologion roquiroment.	*
Application Papers		,
9) The specification is objected to by the Examiner		
10) ☐ The drawing(s) filed on is/are: a) ☐ acce		
Applicant may not request that any objection to the c	•	
Replacement drawing sheet(s) including the correction.		
11)☐ The oath or declaration is objected to by the Exa	aminer. Note the attached Of	TICE Action or form PTO-152.
Priority under 35 U.S.C. § 119		
<ul><li>12) Acknowledgment is made of a claim for foreign</li><li>a) All b) Some * c) None of:</li></ul>	priority under 35 U.S.C. § 11	9(a)-(d) or (f).
1. Certified copies of the priority documents	have been received.	
<ol><li>Certified copies of the priority documents</li></ol>	have been received in Appli	cation No
3  Copies of the certified copies of the priori	ity documents have been rec	eived in this National Stage
application from the International Bureau		
* See the attached detailed Office action for a list of	of the certified copies not rec	eived.
	•	
AM-14-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1		
Attachment(s)		
Notice of References Cited (RTO 900)		nary (PTO-413)
)     Notice of References Cited (PTO-892)	4) ∐ Interview Sumn Paper No(s)/Ma	il Date
<ul> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)</li> <li>Paper No(s)/Mail Date 11/18/03</li> </ul>	Paper No(s)/Ma	il Date nal Patent Application (PTO-152)

Application/Control Number: 10/714,962

Art Unit: 2815

#### **DETAILED ACTION**

### Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

Claims 1, 4, 11, 14, 17, and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chakravorty (US 6,181,569 B1).

Chakravorty shows a structure of a semiconductor device having a semiconductor substrate (se Fig. 4) formed with a plurality of pads 304, and wiring electrically connecting the electrode pads 304 to external electrodes (not shown); the layers of the wiring each having depressed portions located at via holes 309 formed in the insulating layers; the wring formed in a plurality of layers (see Fig. 5), the

Application/Control Number: 10/714,962

Art Unit: 2815

semiconductor device comprising: insulating layers interposed between the layers of the wiring, and between the lowermost layer of the wiring and the semiconductor substrate; the layers of the wiring each having depressed portions located at via holes formed in the insulating layers, the depressed portions connected to the lower layer of the wiring and/or the electrode pads; bump electrodes 313 formed on the depressed portions of the uppermost layer of the wiring; external electrodes (see Fig. 8d) formed on the top surfaces of the bump electrodes 313; and a sealing layer 312 formed over the uppermost layer of the wiring so as to expose the top surface of the bump electrodes 313. However, Chakravorty fails to show an external circuit board including conductive patterns with the connection from the wiring. Saito shows in Fig. 3 a connection between a semiconductor element 4 to a printed circuit board with electrodes 6. Hence, it would have been obvious for Chakarvorty to include a circuit board, as is notoriously known.

Concerning claims 11 and 17, please see the above discussion under claim 1.

#### Allowable Subject Matter

2. Claims 2, 3, 5-10, 12, 13, 15, 18, and 19 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The applied reference(s) fail to teach and/or suggest the limitations as set forth in claims 2, 3, 5-10, 12, 13, 15, 18 and 19.

Application/Control Number: 10/714,962 Page 4

Art Unit: 2815

3. Claim16 is allowed.

The following is an examiner's statement of reasons for allowance: the applied reference fails to further teach and/or suggest the limitations as set forth in claim 16, for example wherein the distances from a neutral point of a thermal stress of the semiconductor device to an arbitrary pair of bump electrodes among electrodes are set as  $H_1$  and  $H_2$ , the length of the pair of bump electrodes are set as  $H_1$  and  $H_2$ , the length of the pair of bump electrodes are set as  $H_1$  and  $H_2$ , then  $H_1 \le H_2$ .

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

The references of interest are cited: Regarding the wiring layers and external bumps, please see Satoh et al. (US 6,621,154 B1), Kikuchi (US 2003/0102551A1), Shinogi et al. (US 6,479,900 B1), Matsuda et al. (US 5,726,489), Sawai et al. (US 5,554,887), Yamaji et al. (US 6,159,837), and Kawashima (US 6,559,540 B2).

## Telephone Inquiry Contacts

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jasmine J Clark whose telephone number is (571) 272-1726. The examiner can normally be reached on Flex.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jjbc/05/29/04

JASMINE CLARK PRIMARY EXAMINER